

AMENDMENTS TO THE SPECIFICATION

IN THE SPECIFICATION:

Amend the paragraph beginning on page 6, line 9, as follows:

D' This photocoupling device is manufactured, in the same manner as a 4-pin photocoupling device as shown in Figs. 10 and 11, through the steps of: mounting a light receiving element (not shown), a light emitting element 101 and another element 111 on specified headers 109a and 109c and connecting to lead terminals 103a, 103c and 113a; wire-bonding the light receiving element, the light emitting element 101 and the other element 111 on specified headers 109b, 109d and so on with wires 125a, 125b and so on and connecting to lead terminals 103b, 103d and 113b; and if necessary, pre-coating and so on. After that, lead frames on the input section side and on the output section side are opposed to each other, and primary molding is performed in a state where the light emitting face of the light emitting element 101 is opposed to the light receiving face of the light receiving element. After this primary molding, burr removal and tie-bar cutting are done at the same time. Next, secondary molding is done, and burr removal and tie-bar cutting are done at the same time as well.